

Title (en)

A METHOD AND DEVICE FOR REMOVING A SURFACE MOUNTED COMPONENT FROM A CIRCUIT BOARD

Title (de)

VERFAHREN UND VORRICHTUNG ZUR ENTFERNUNG EINER OBERFLÄCHENMONTIERTEN KOMPONENTE VON EINER LEITERPLATTE

Title (fr)

PROCEDE ET DISPOSITIF PERMETTANT D'ENLEVER UN COMPOSANT MONTE EN SURFACE D'UNE CARTE IMPRIMEE

Publication

EP 0764394 A1 19970326 (EN)

Application

EP 95902374 A 19941124

Priority

- SE 9401124 W 19941124
- SE 9303909 A 19931125

Abstract (en)

[origin: WO9515073A1] A method and a device for removing a surface mounted component (11) from a circuit board (10), the component being attached by means of an adhesive joint. According to the method the component and the adhesive joint are subjected to a thermal shock by being cooled down and are imparted with such internal mechanical stresses that the component is loosened. The device comprises means (16, 17, 18) for supplying cooling medium to the component (11), shielding means (15) for shielding the component (11) from other components (12) and control means (19) for controlling the supply of the cooling medium and for positioning the shielding means (15) in relation to the component (11).

IPC 1-7

H05K 13/00; **H05K 13/04**

IPC 8 full level

H05K 13/04 (2006.01)

CPC (source: EP)

H05K 13/0486 (2013.01)

Citation (search report)

See references of WO 9515073A1

Designated contracting state (EPC)

CH DE FR GB IT LI

DOCDB simple family (publication)

WO 9515073 A1 19950601; EP 0764394 A1 19970326; SE 502007 C2 19950710; SE 9303909 D0 19931125; SE 9303909 L 19950526

DOCDB simple family (application)

SE 9401124 W 19941124; EP 95902374 A 19941124; SE 9303909 A 19931125